

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently amended): A probe card structure comprising:

a probe section sections comprising having an insulated circuit board, ~~& a probe probes~~ of silicon material which are being formed on the said insulated circuit board, ~~and are in contact for contacting with~~ the a pad of a device to be measured, ~~&~~ and a conductive wiring electrically connected in electrical communication with to the said probe probes and formed disposed on the said insulated circuit board;

a supporting structure structures which for supporting support each of the said probe section sections;

a fixing structure which for fixes fixing the a plurality of said supporting structures together;

a printed circuit which is having a conductive wiring connected to the said fixing structure, said

printed circuit and is being electrically connected to
~~the a~~ measurement device for transmitting ~~the a~~
measurement signal signals to the said device ~~to be~~
being measured, ~~and has conductive wiring;~~ and

a wiring connection means for electrically
connecting ~~the~~ said conductive wiring of ~~the~~ said probe
probes and ~~the~~ said conductive wiring in communication
with ~~of~~ the said printed circuit.

Claim 2 (Currently amending): The probe card
structure ~~according to~~ of claim 1 ~~Claim 1~~, wherein ~~the~~ said
supporting structures structure and ~~the~~ said
fixing structure are made of ~~one~~ a material selected
from the group consisting of invar, kovar, quartz, and
ceramic, and any combinations thereof.

Claim 3 (Currently amended): The probe card
structure ~~according to~~ Claim 1 of claim 1, wherein ~~the~~ said
conductive wiring of ~~the~~ said probe section and
~~the~~ said conductive wiring of ~~the~~ said printed circuit
are electrically connected by a sub printed circuit,
said sub printed circuit being selected from the group
consisting of ~~which can be~~ a flexible printed circuit,
a ~~or~~ rigid printed circuit board, and any combinations
thereof.

Claim 4 (Currently amended): The probe card structure ~~according to~~ of Claim 3, claim 3, wherein ~~the~~ said conductive wiring of ~~the~~ said probe section and ~~the~~ a conductive wiring of ~~the~~ said sub printed circuit are electrically connected by a metallic wire, said metallic wire being formed by ~~the~~ a wire bonding method.

Claim 5 (Currently amended): The probe card structure ~~according to~~ Claim 3, of claim 3, wherein ~~the~~ said conductive wiring of ~~the~~ said probe section and ~~the~~ a conductive wiring of ~~the~~ a flexible circuit are electrically connected by ~~the~~ an anisotropic conducting film.

Claim 6 (Currently amended): The probe card structure ~~according to~~ Claim 3, of claim 3, wherein further comprising at least one capacitor ~~is installed~~ to reduce ~~the~~ an electric noise on ~~the~~ a flexible printed circuit.

Claim 7 (Currently amended): The probe card structure ~~according to~~ Claim 3, of claim 3, wherein further comprising a contact pad of ~~the~~ said sub printed circuit and ~~the~~ a contact pad of ~~the~~ said insulated circuit board are electrically connected by a pogo pin.

Claim 8 (Currently amended): The probe card structure ~~according to Claim 3[~,]~~ of claim 3, wherein further comprising ~~the~~ a contact pad of ~~the~~ said sub printed circuit and ~~the~~ a contact pad of ~~the~~ said insulated circuit board ~~are~~ electrically connected by an perpendicular conductor of silicon rubber material ~~which~~ conducts for conducting electricity between a top and a bottom surface through a plurality of vertically embedded metallic wires ~~with~~ having a diameter of 35 μm or less, said plurality of vertically embedded metallic wires being positioned in an array of a 0.07 [[~]] through 0.45mm matrix.

Claim 9 (Currently amended): The probe card structure ~~according to Claim 3,~~ of claim 3, wherein further comprising a plating layer is formed on ~~the~~ said probe of ~~the~~ said probe section and ~~the~~ said conductive wiring of said probe section.

Claim 10 (Currently amended): The probe card structure ~~according to Claim 9,~~ of claim 9, wherein ~~the~~ said plating layer is formed by selected from the group consisting of a nickel plating layer, ~~or~~ a gold plating layer, and any combinations thereof.

Claim 11 (Currently amended): The probe card structure ~~according to Claim 10,~~ of claim 10, wherein further comprising a groove is formed at ~~the~~ a tip of

~~the said probe probes before the said plating layer is formed.~~

Claim 12 (Currently amended): The probe card structure ~~according to Claim 1, of claim 1, wherein further comprising~~ at least a screw is installed in the ~~said supporting structure to for adjust adjusting the 3-dimensional a locations location of the said supporting structures structure and the said fixing structures structure, said location being adjustable in three dimensions.~~

Claim 13 (Currently amended): The probe card structure ~~according to Claim 1, of claim 1, wherein further comprising~~ at least a screw is installed in the ~~said fixing structure, said screw to for adjusting adjust the 3-dimensional a location locations of the said supporting structures structure and the said fixing structures structure, said location being adjustable in three dimensions.~~